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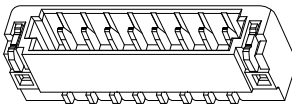
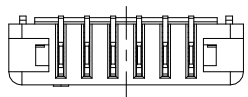
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NOTES:

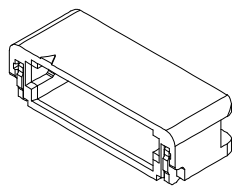
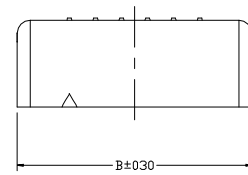
1.MATERIAL

- 1.1 Insulator: LCP+G/F30%,UL94 V-0,Black
- 1.2 Contact: Copper Alloy, Gold Flash over Ni

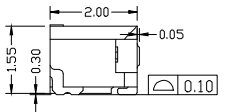
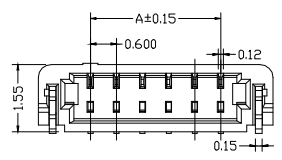
2.ELECTRICAL:

- 2.1 Rating Current: 0.2 AMPS/contact max.
- 2.2 Rating Voltage: 30 V AC/DC
- 2.3 Contact Resistance: 20 mΩ /contact max.
- 2.4 Insulation Resistance: 100 MΩ min.
- 2.5 Withstanding Voltage: 200V AC/minute
- 4.Operating Temperature: -25°C To +85°C
- 5.Packing: Tape&Reel

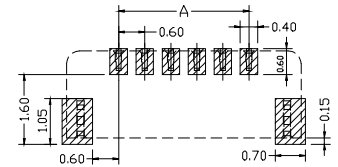
B



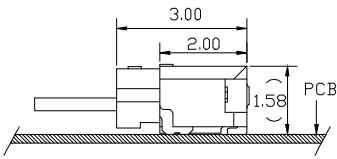
C



D



Recommended P.C.B Layout
General Tolerance±0.05



Mated Condition

② Poles	Dimensions(mm)		Poles	Dimensions(mm)	
	A	B		A	B
02	0.60	3.00	12	6.60	9.00
03	1.20	3.60	13	7.20	9.60
04	1.80	4.20	14	7.80	10.20
05	2.40	4.80	15	8.40	10.80
06	3.00	5.40	16	9.00	11.40
07	3.60	6.00	17	9.60	12.00
08	4.20	6.60	18	10.20	12.60
09	4.80	7.20	19	10.80	13.20
10	5.40	7.80	20	11.40	13.80
11	6.00	8.40	22	12.60	15.00

E

F

G

RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
X.	±0.35
X.X	±0.25
X.XX	±0.20
X.XXX	±0.15
DIM	TOL
Angle	TOL

						Date	Name	Description: Wire to Board Wafer SMT / Right Angle Pitch 0.60 mm		
						Drawn	09.23.2022		Winnie	
						Approved	10.10.2023		Peter	
								ASSMANN WSW-NO.		
								A-WBP-AA001EA-xxSR01		
								Drawing-No.	ASS 9485 CO	rev02
								Customer-No.		
									SHEET	1 / 2



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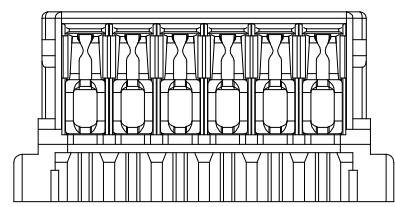
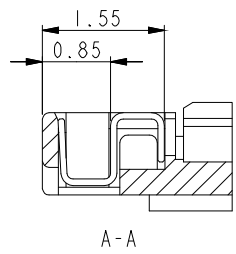
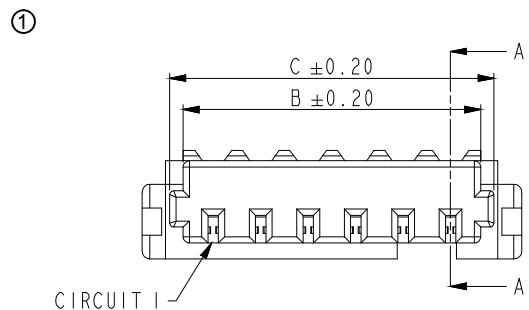
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A

A



NOTES:

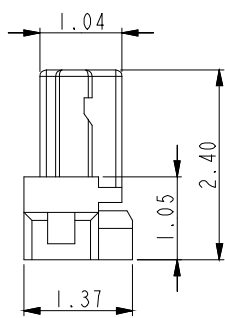
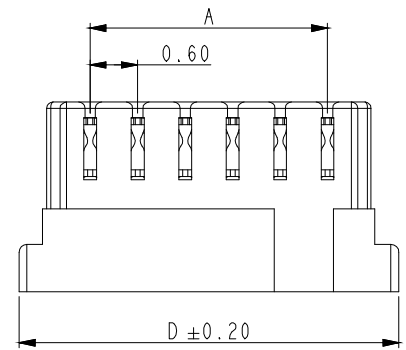
- 1.MATERIAL
 - 1.1 Insulator:LCP,UL94 V-0,Black
 - 1.2 Contact:Copper Alloy, Gold Flash over Ni
- 2.ELECTRICAL
 - 2.1 Rating Current:0.2A AC/DC
 - 2.2 Rating Voltage:30 V AC/DC
 - 2.3 Contact Resistance:30 mΩ Max.
 - 2.4 Insulation Resistance:100 MΩ min.
 - 2.5 Withstanding Voltage:200V AC/minute
- 3.Applicable Wire:AWG#34
- 4.Insulation O.D.:∅0.32mm
- 5.Operating Temperature: -25°C To +85°C
- 6.Packing: PE bag

B

B

C

C

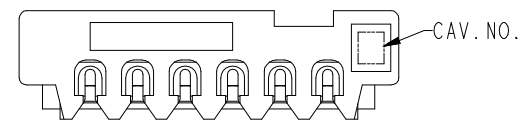


D

D

E

E



②	PIN	DIM.(mm)				PIN	DIM.(mm)			
		A	B	C	D		A	B	C	D
02	0.60	1.35	1.70	2.40	12	6.60	7.35	7.70	8.40	
03	1.20	1.95	2.30	3.00	13	7.20	7.95	8.30	9.00	
04	1.80	2.55	2.90	3.60	14	7.80	8.55	8.90	9.60	
05	2.40	3.15	3.50	4.20	15	8.40	9.15	9.50	10.20	
06	3.00	3.75	4.10	4.80	16	9.00	9.75	10.10	10.80	
07	3.60	4.35	4.70	5.40	17	9.60	10.35	10.70	11.40	
08	4.20	4.95	5.30	6.00	18	10.20	10.95	11.30	12.00	
09	4.80	5.55	5.90	6.60	19	10.80	11.55	11.90	12.60	
10	5.40	6.15	6.50	7.20	20	11.40	12.15	12.50	13.20	
11	6.00	6.75	7.10	7.80	22	12.60	13.35	13.70	14.40	

F

F

G

G

RoHS compliant
unit:mm

Scale	Free
TOLERANCE	
X.	±0.35
X.X	±0.25
X.XX	±0.20
X.XXX	±0.15
DIM	TOL
Angle	TOL

②	Update the dimension and delete the 21 pin housing	10.10.2023	Peter
①	Added the page 2	09.27.2022	Peter
①	Drawn	09.23.2022	Winnie
Id.	modification	Date	Name

Date Name

Drawn 09.23.2022 Winnie

Approved 10.10.2023 Peter

ASSMANN
WSW components

Description: Wire to Board Housing
Pitch 0.60 mm IDC Type

ASSMANN WSW-NO.
A-WBH-AA001EG-xxIB01

Drawing-No.
ASS 9485 CO rev02

Customer-No. SHEET 2 / 2

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